
SmartBond Flash Programmer Tool

Release Notes

This document contains the release notes for SmartBond™ Flash Programmer tool, version 1.0.12 GA.

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1. Terms and Definitions

GA	General access
LA	Limited access
FW	Firmware
SDK	Software Development Kit
URL	Uniform Resource Locator

2. Release Data

Table 1. Release data

Operating System	Windows - Linux - macOS (x86_64)
Operating System Version	64 bit (ARM64 for macOS - can be supported through Rosetta Translation Support option)
Software Release Date	March 5, 2024
Software Version Number	1.0.12
Software Release Type (Note 1)	FULL GA

Note 1 Releases can be of the following types: FULL (GA), FULL (LA), RELEASE CANDIDATE, ENGINEERING, PATCH or BINARY

3. License

Licenses covering this SmartBond™ Flash Programmer release are listed in the licensing.txt file located under the 'common_resources' folder of the installation directory.

4. Release Description

4.1 Overview

This is a GA release of SmartBond™ Flash Programmer tool.

This release:

- Supports DA14592 chips with standard eFlash option.
- Supports DA14535 chips.
- Supports DA1469x with PUYA flash option.
- Supports DA1469x-FabPort chips.
- Supports DA14585/586 chips.
- Supports DA1453x chips.
- Supports latest updates regarding corporate branding details.



Figure 1. SmartBond™ Flash Programmer tool

4.2 New and updated features of 1.0.12

Table 2. 1.0.12 new features

Feature number	Description
112_01	Add Support for DA14592 chips with eflash option.
112_02	Apply latest updates regarding Renesas' branding details.
112_03	Migrate URL link redirects under Renesas domain.
112_04	Migrate JLink bundles to meet the latest compatible version.
112_05	Migrate to a Renesas default tool installation directory.
112_06	Add Support for DA14535 chips.

4.3 Fixes and improvements since 1.0.10

Table 3. 1.0.12 fixes and improvements

Fix number	Description
112-01	Apply important hot-fixes related to used software dependencies.
112-586	Fix Erase-Program-Jlink issue on DA1453x dev-kit.

4.4 Known issues of 1.0.12

Table 4. 1.0.12 known issues

Issue number	Description
	<No known issues>

4.5 Known limitations of 1.0.12

Table 5. 1.0.12 known limitations

Issue number	Description

5. Release History

5.1 1.0.10

Version 1.0.10 of SmartBond™ Flash Programmer tool was released on Jul 22, 2023.

5.1.1 Overview

This was a FULL (GA) release of SmartBond™ Flash Programmer tool. This release:

- Supports DA1469x with PUYA flash option.
- Supports DA1469x-FabPort chips.
- Supports DA14585/586 chips.
- Supports DA1453x chips.

5.1.2 New and updated features of 1.0.10

Table 6. 1.0.10 new features

Feature number	Description
110_01	Add support for PUYA flash device with DA1469x chips.
110_02	Add support for visual dynamic selection in UI, based on supported hardware setup.

5.1.3 Fixes and improvements since 1.0.8

Table 7. 1.0.10 fixes and improvements

Fix number	Description

5.1.4 Known issues of 1.0.10

Table 8. 1.0.10 known issues

Issue number	Description
	<No known issues>

5.1.5 Known limitations of 1.0.10

Table 9. 1.0.10 known limitations

Issue number	Description
	<No known limitations>

5.2 1.0.8

Version 1.0.8 of SmartBond™ Flash Programmer tool was released on Feb 11, 2022.

5.2.1 Overview

This was a FULL (GA) release of SmartBond™ Flash Programmer tool. This release:

- Supports DA1469x and DA1469x-FabPort chips.
- Supports DA14585/586 chips.
- Supports DA1453x chips.

5.2.2 New and updated features of 1.0.8

Table 10. 1.0.8 new features

Feature number	Description
108_01	Add support for DA1469x-FabPort chips.
108_02	Add support for new Windows 64-bit Signing Certificate.

5.2.3 Fixes and improvements since 1.0.6

Table 11. 1.0.8 fixes and improvements

Fix number	Description
108/01	Update support packs
108/02	Change default QSPI memory size for DA1469x from 0x2000000 to 0x400000.
108/03	Upgrade FTDI driver to version 2.12.36.4 for windows installations.

5.2.4 Known issues of 1.0.8

Table 12. 1.0.8 known issues

Issue number	Description
	<No known issues>

5.2.5 Known limitations of 1.0.8

Table 13. 1.0.8 known limitations

Issue number	Description
	<No known limitations>

5.3 1.0.6

Version 1.0.6 of SmartBond™ Flash Programmer tool was released on Apr 23, 2021.

5.3.1 Overview

This was a FULL (GA) release of SmartBond™ Flash Programmer tool. This release:

- Supports DA14585/586 & DA1469x chips.
- Supports DA1453x chips

5.3.2 New and updated features of 1.0.6

Table 14. 1.0.6 new features

Feature number	Description
106_01	Add support for DA14585/586, DA1469x chips.
106_02	Add support for organization in groups of remote site resources.
106_03	Add support for JTAG auto detection mechanism.
106_04	Add support for manual selection to one of the supported device types.
106_05	Add support for License file revision and history.
106_06	Add support for MKImage parametric options for DA1469x device.

5.3.3 Fixes and improvements since 1.0.4

Table 15. 1.0.6 fixes and improvements

Fix number	Description
106/01	Fix issue with PKG script during installation.
106/02	Fix issue with JLink popups.

5.3.4 Known issues of 1.0.6

Table 16. 1.0.6 known issues

Issue number	Description
	<No known issues>

5.3.5 Known limitations of 1.0.6

Table 17. 1.0.6 known limitations

Issue number	Description
	<No known limitations>

5.4 1.0.4

Version 1.0.4 of SmartBond™ Flash Programmer tool was released on Apr 9, 2020.

5.4.1 Overview

This was a FULL (GA) release of SmartBond™ Flash Programmer tool. This release:

- Supports DA1453x chips.

5.4.2 New and updated features of 1.0.4

Table 18. 1.0.4 new features

Feature number	Description

5.4.3 Fixes and improvements since 1.0.2

Table 19. 1.0.4 fixes and improvements

Fix number	Description
104/01	Fixes issue with non-bootable image support.

5.4.4 Known issues of 1.0.4

Table 20. 1.0.4 known issues

Issue number	Description
	<No known issues>

5.4.5 Known limitations of 1.0.4

Table 21. 1.0.4 known limitations

Issue number	Description
	<No known limitations>

5.5 1.0.2

Version 1.0.2 of SmartBond™ Flash Programmer tool was released on Mar 3, 2020.

5.5.1 Overview

This was a FULL (GA) release of SmartBond™ Flash Programmer tool.

5.5.2 New features of 1.0.2

Table 22. 1.0.2 new features

Feature number	Description
102_01	Add support for DA1453x family of chips.
102_02	Support connection to remote site and dynamic fetching of binary resources.
102_03	Support Programming/Erasing Flash operations.
102_04	Support Flash Programming with bootable option.
102_05	Support a thin installer that fetches installation binaries from a remote site.

5.5.3 Known issues of 1.0.2

Table 23. 1.0.2 known issues

Issue number	Description
	<No known issues>

5.5.4 Known limitations of 1.0.2

Table 24. 1.0.2 known limitations

Issue number	Description
	<No known limitations>

Appendix A Software Versioning Rules

This describes the software version numbers and does not apply to documentation version numbers (as found in the footer of this document).

Each software version number string consists of four numbers: MAJOR. BRANCH. MINOR. and BUILD.

#MAJOR: It is increased (by one only) if the project undergoes a major modification, for example major ROM changes. It usually changes only when the project sources undergo major restructuring affecting most of the repository. It is initialized at 1.

#BRANCH: Used in the case of concurrent projects that for special reasons need to be spun off the major repository. It corresponds to different versions of the repository code that have to be supported concurrently. In this case each branch number corresponds to a different GIT branch. The basic project has BRANCH id 0.

#MINOR: Odd numbers indicate Engineering (or Patch or Binary) versions, even numbers indicate Full release versions or Release Candidates of Full versions. Each Full release increases this number by one. After the Full release, the number is increased by one again. Therefore, Project releases correspond to release numbers like 2.0.1.xxx, 2.0.2.xxx. etc. The #MINOR number is initialized at 1.

#BUILD: The # BUILD number increases by one at every repository update and thus indicates the total number of changes since repository initialization. The BUILD number is initialized at 1.

Document Revision History

This section summarizes the changes made to this document and not to the Software that this document describes.

Revision	Date	Description
06.02	Mar 05, 2024	Introduce hot-fixes for v1.0.12
06.00	Dec 21, 2023	Introduce changes for v1.0.12
05.00	Jul 22, 2023	Introduce changes for v1.0.10
04.00	Feb 11, 2022	Introduce changes for v1.0.8
03.00	Apr 23, 2021	Introduce changes for v1.0.6
02.00	Apr 9, 2020	Introduce changes for v1.0.4
01.00	Mar 3, 2020	First version. Introduce changes for v1.0.2

Status Definitions

Status	Definition
DRAFT	The content of this document is under review and subject to formal approval, which may result in modifications or additions.
APPROVED or unmarked	The content of this document has been approved for publication.

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